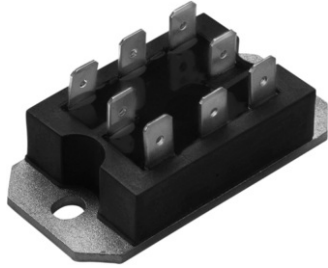


Passivated Assembled Circuit Elements, 25 A



PACE-PAK (D-19)

FEATURES

- Glass passivated junctions for greater reliability
- Electrically isolated base plate
- Available up to 1200 V_{RRM}/V_{DRM}
- High dynamic characteristics
- Wide choice of circuit configurations
- Simplified mechanical design and assembly
- UL E78996 approved
- RoHS compliant


RoHS
COMPLIANT

DESCRIPTION

The P100 series of integrated power circuits consists of power thyristors and power diodes configured in a single package. With its isolating base plate, mechanical designs are greatly simplified giving advantages of cost reduction and reduced size.

Applications include power supplies, control circuits and battery chargers.

PRODUCT SUMMARY

I_D	25 A
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MAJOR RATINGS AND CHARACTERISTICS

PARAMETER	CHARACTERISTICS	VALUES	UNITS
I_D	85 °C	25	A
I_{FSM}	50 Hz	357	A
	60 Hz	375	
I^2t	50 Hz	637	A ² s
	60 Hz	580	
$I^2\sqrt{t}$		6365	A ² √s
V_{RRM}	Range	400 to 1200	V
V_{ISOL}		2500	V
T_J		- 40 to 125	°C

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS

TYPE NUMBER	V_{RRM}/V_{DRM} , MAXIMUM REPETITIVE PEAK REVERSE AND PEAK OFF-STATE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} MAXIMUM AT T_J MAXIMUM mA
P101, P121, P131	400	500	10
P102, P122, P132	600	700	
P103, P123, P133	800	900	
P104, P124, P134	1000	1100	
P105, P125, P135	1200	1300	



ON-STATE CONDUCTION					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum DC output current at case temperature	I_D	Full bridge		25	A
				85	°C
Maximum peak, one-cycle non-repetitive on-state or forward current	I_{TSM}, I_{FSM}	t = 10 ms	No voltage reappplied	Sinusoidal half wave, initial $T_J = T_J$ maximum	A
		t = 8.3 ms			
		t = 10 ms	100 % V_{RRM} reappplied		
		t = 8.3 ms			
Maximum I^2t for fusing	I^2t	t = 10 ms	No voltage reappplied	Sinusoidal half wave, initial $T_J = T_J$ maximum	A ² s
		t = 8.3 ms			
		t = 10 ms	100 % V_{RRM} reappplied		
		t = 8.3 ms			
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reappplied I^2t for time tx = $I^2\sqrt{t} \cdot \sqrt{tx}$		6365	A ² √s
Maximum value of threshold voltage	$V_{T(TO)}$	$T_J = 125\text{ °C}$		0.82	V
Maximum level value of on-state slope resistance	r_{t1}	$T_J = 125\text{ °C}$, average power = $V_{T(TO)} \times I_{T(AV)} + r_t + (I_{T(RMS)})^2$		12	mΩ
Maximum on-state voltage drop	V_{TM}	$T_J = 25\text{ °C}$, $I_{TM} = \pi \times I_{T(AV)}$		1.35	V
Maximum forward voltage drop	V_{FM}	$T_J = 25\text{ °C}$, $I_{TM} = \pi \times I_{T(AV)}$		1.35	V
Maximum non-repetitive rate of rise of turned-on current	dl/dt	$T_J = 125\text{ °C}$ from 0.67 V_{DRM} $I_{TM} = \pi \times I_{T(AV)}$, $I_g = 500\text{ mA}$, $t_r < 0.5\text{ }\mu\text{s}$, $t_p > 6\text{ }\mu\text{s}$		200	A/μs
Maximum holding current	I_H	$T_J = 25\text{ °C}$ anode supply = 6 V, resistive load, gate open		130	mA
Maximum latching current	I_L	$T_J = 25\text{ °C}$ anode supply = 6 V, resistive load			

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = 125\text{ °C}$, exponential to 0.67 V_{DRM} gate open		200	V/μs
Maximum peak reverse and off-state leakage current at V_{RRM}, V_{DRM}	I_{RRM}, I_{DRM}	$T_J = 125\text{ °C}$, gate open circuit		10	mA
Maximum peak reverse leakage current	I_{RRM}	$T_J = 25\text{ °C}$		100	μA
RMS isolation voltage	V_{ISOL}	50 Hz, circuit to base, all terminals shorted, $T_J = 25\text{ °C}$, t = 1 s		2500	V



TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	P_{GM}			8	W
Maximum average gate power	$P_{G(AV)}$			2	
Maximum peak gate current	I_{GM}			2	A
Maximum peak negative gate voltage	$-V_{GM}$			10	V
Maximum gate voltage required to trigger	V_{GT}	$T_J = -40\text{ °C}$	Anode supply = 6 V resistive load	3	V
		$T_J = 25\text{ °C}$		2	
		$T_J = 125\text{ °C}$		1	
Maximum gate current required to trigger	I_{GT}	$T_J = -40\text{ °C}$		90	mA
		$T_J = 25\text{ °C}$		60	
		$T_J = 125\text{ °C}$		35	
Maximum gate voltage that will not trigger	V_{GD}	$T_J = 125\text{ °C}$, rated V_{DRM} applied		0.2	V
Maximum gate current that will not trigger	I_{GD}			2	mA

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction operating and storage temperature range	T_J, T_{Stg}			- 40 to 125	°C
Maximum thermal resistance, junction to case per junction	R_{thJC}	DC operation		2.24	K/W
Maximum thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth and greased		0.10	
Mounting torque, base to heatsink ⁽¹⁾				4	Nm
Approximate weight				58	g
				2.0	oz.

Note

⁽¹⁾ A mounting compound is recommended and the torque should be checked after a period of 3 hours to allow for the spread of the compound

CIRCUIT TYPE AND CODING (1)			
	CIRCUIT "0"	CIRCUIT "2"	CIRCUIT "3"
Terminal positions			
Schematic diagram			
	Single phase hybrid bridge common cathode	Single phase hybrid bridge doubler	Single phase all SCR bridge
Basic series	P10.	P12.	P13.
With voltage suppression	P10.K	P12.K	P13.K
With freewheeling diode	P10.W	-	-
With both voltage suppression and freewheeling diode	P10.KW	-	-

Note

(1) To complete code refer to Voltage Ratings table, i.e.: For 600 V P10.W complete code is P102W

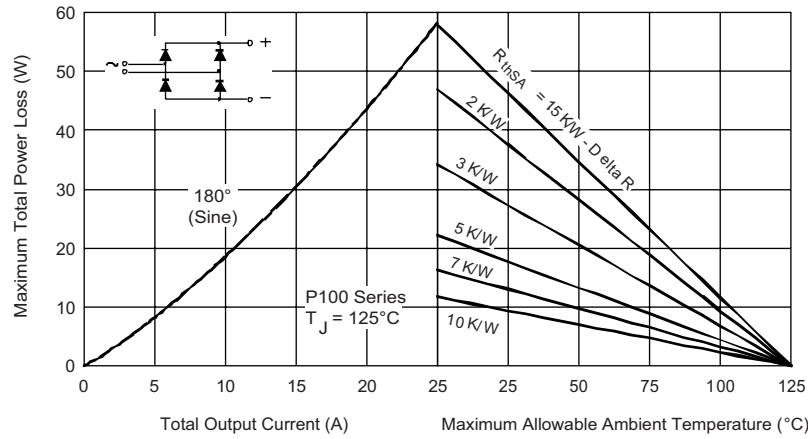


Fig. 1 - Current Ratings Nomogram (1 Module Per Heatsink)

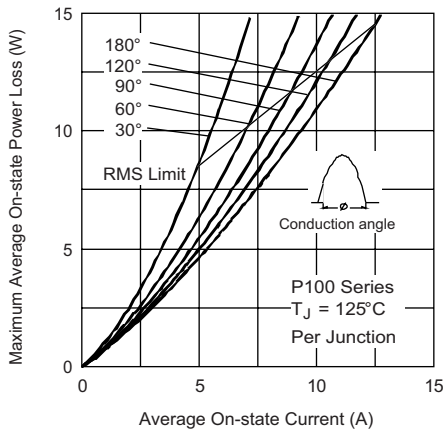


Fig. 2 - On-State Power Loss Characteristics

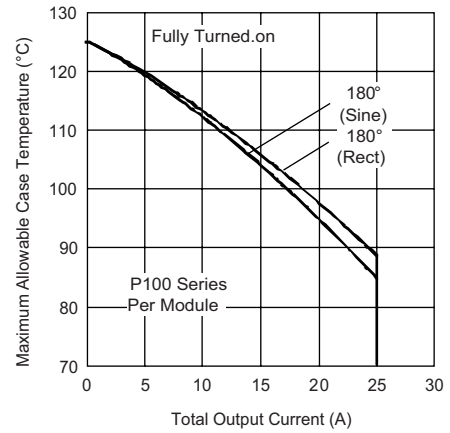


Fig. 4 - Current Ratings Characteristics

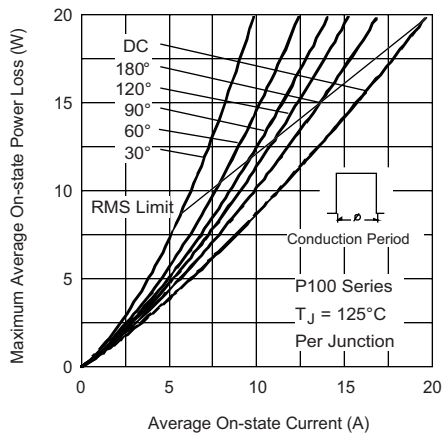


Fig. 3 - On-State Power Loss Characteristics

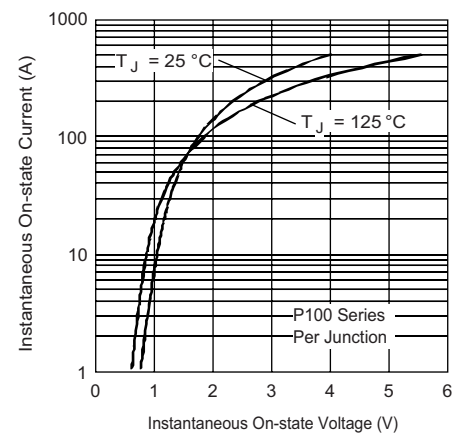


Fig. 5 - On-State Voltage Drop Characteristics

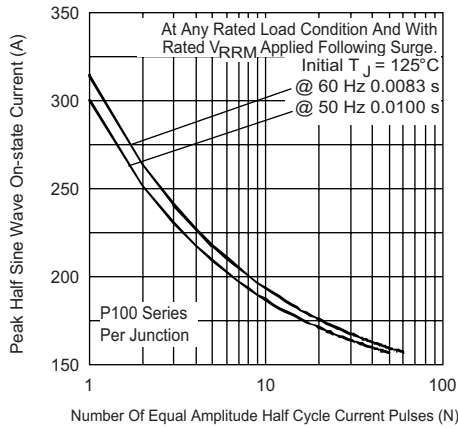


Fig. 6 - Maximum Non-Repetitive Surge Current

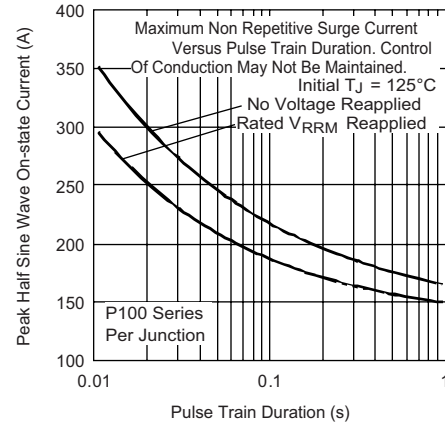


Fig. 7 - Maximum Non-Repetitive Surge Current

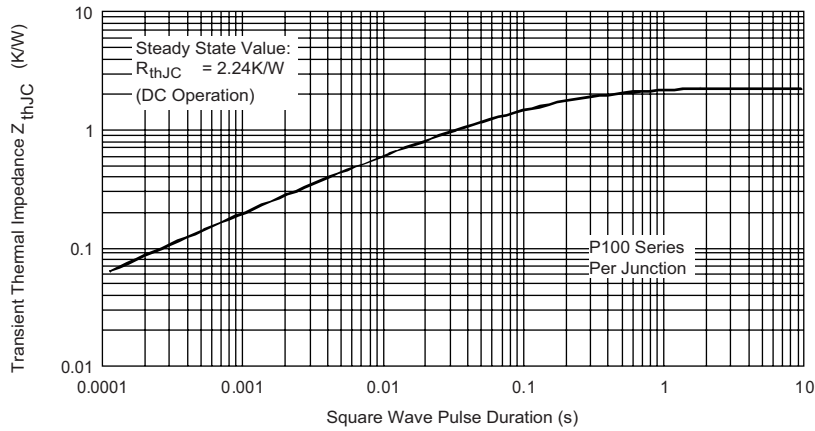


Fig. 8 - Thermal Impedance Z_{thJC} Characteristics

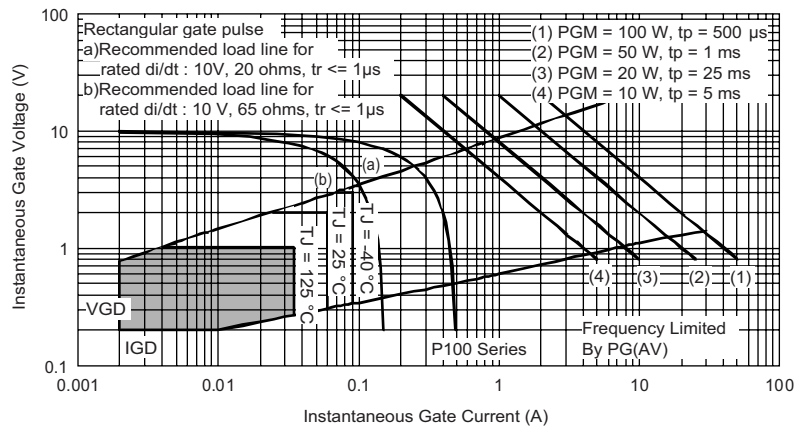


Fig. 9 - Gate Characteristics

LINKS TO RELATED DOCUMENTS

Dimensions

<http://www.vishay.com/doc?95335>